

~~Amendments to the Specification:~~

page 2, insert below title

~~Please add the following paragraph before paragraph [0001] (as numbered in U.S. Patent Publication No. US 2002/0179014):~~

IDC-a1,AMD

CLAIM TO PRIORITY

This application is a continuation application of U.S. Patent Application No. 10/195,357, filed on July 16, 2002, now U.S. Patent No. 6,641,672, which is a continuation application of U.S. Patent Application No. 09/589,635, filed on June 7, 2000, now U.S. Patent No. 6,440,219.

page 4, lines 7-16

~~Please replace paragraph [0006] (as numbered in U.S. Patent Publication No. US 2002/0179014) with the following amended paragraph:~~

IDC-a2,AMD

[0006] As with the other prior art, the major drawback of this shield ring is that eventually there will be some deposition at the edge of the shield ring at the locations where the shield ring contacts the wafer. This gap between the shield ring and the wafer caused by material deposit will be widen quickly with time due to more and more material deposition. This process causes the shield ring to lose contact with the wafer and thus no longer performs the shielding action. The apparatus will need to shut down, the chamber 70 vented, and the shield ring manually replaced. Then the chamber 70 will be pump down and the system needs conditioning for process qualification before running again. This causes a significant lost in productivity.

page 11, lines 12-17

~~Please replace paragraph [0040] (as numbered in U.S. Patent Publication No. US 2002/0179014) with the following amended paragraph:~~

IDC-a3,AMD

[0040] FIG. 4 shows the present invention of the replaceable shielding apparatus in the disengaged position. The susceptor lift 146 moves the shaft 148 and the workpiece support 130, leaving the replaceable shield 150 in the disengaged position. The shield support 172 separates the shield 150 from the workpiece 110 to allow the removal of the shield 150. The shield support 172 is connected to a stationary wall 176 such as the chamber wall of the chamber 200.

page 11, line 19 through page 12, line 4

~~Please replace paragraph [0041] (as numbered in U.S. Patent Publication No. US 2002/0179014) with the following amended paragraph:~~

[0041] FIG. 5 shows the present invention of the replaceable shielding apparatus in the disengaged position with the shield restraint clamp means. The shield restraint clamp 180 is supported by the shield restraint clamp support 182 in the disengaged position to separate the shield restraint clamp 180 from the shield 150 to allow the removal of the shield 150. The shield restraint pressing means 190, in this case an extended spring, connects the shield restraint clamp 180 to the wall 176 of the chamber 200 for pressing the shield 150 against the workpiece 110 in the engaged position. The pin 187 allows the alignment of the shield restraint clamp 180 between the engaged and disengaged positions. Similarly, the pin 185 allows the alignment of the shield 150 between the engaged and disengaged positions. The shield support 172 is connected to the stationary wall 176. In some aspects of the invention, the shield support 172 is connected to the shield restraint clamp means 180 (not shown).

page 12, lines 6-18

~~Please replace paragraph [0042] (as numbered in U.S. Patent Publication No. US-2002/0179014) with the following amended paragraph:~~

IDC-a5,AMD

[0042] FIG. 6 shows the present invention of the replaceable shielding apparatus in the engaged position with the purging gas. The purging gas 196 enters from outside the system to the cavity 195 defined by the workpiece support 130, the workpiece 110, the shield 150 and the shield restraint clamp 180. The shield restraint clamp 180 is resting on the workpiece support 130 at location 199, therefore the purging gas leakage should be minimum. The opening in the workpiece support 130 for the entrance of the shield support 172 might provide a high leakage path for the purging gas, but this opening is still small, about 1/4" in diameter. An alternative to eliminate this leakage path is to connect the shield support to the shield restraint clamp 180 (not shown). The cavity 195 retains the purging gas, creates a higher pressure in the cavity 195 than in the chamber 200, therefore further preventing the deposition at the shielding portion of the workpiece.